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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

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| APPL NUM 10008700 | FILING DATE 12/07/2001 | CLASS 438 | SUBCLASS 764 | GAU 2812 | EXAMINER L44 |
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2825

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:
REPUBLIC OF KOREA 2000-74315 12/07/2000

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| PG-PUB DO NOT PUBLISH <input type="checkbox"/> | RESCIND <input type="checkbox"/> |
| Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no | ATTORNEY DOCKET NO 5648-905 |
| 35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no | |
| Verified and Acknowledged Examiners's initials | |
| TITLE: Methods of manufacturing integrated circuit devices having an encapsulated insulation layer | |

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436 (Rev. 12-94)

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|---|-----------|--|----------------------|
| NOTICE OF ALLOWANCE MAILED | | CLAIMS ALLOWED | |
| Assistant Examiner | | Total Claims | Print Claim for O.G. |
| | | DRAWING | |
| Amount Due | Date Paid | Sheets Drwg. | Figs. Drwg. |
| <input type="checkbox"/> TERMINAL DISCLAIMER | | Print Fig. | |
| | | Application Examiner | |
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